

12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20170609001A Qualification of TIPI as additional Assembly and Test Site for Select Devices Change Notification / Sample Request

Date: July 18, 2018

To: PREMIER FARNELL PCN

Dear Customer:

Revision A is to update the description of change to provide correction on the pin 1 marking differences between sites. We apologize for any inconvenience this may have caused.

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The proposed first ship date is indicated on page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN www admin team@list.ti.com).

Sincerely,

PCN Team SC Business Services

20170609001A Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TPS561201DDCT	null
TPS561208DDCT	null
TPS562201DDCT	null
TPS562208DDCT	null
TPS563201DDCT	null
TPS563208DDCT	null

Technical details of this Product Change follow on the next page(s).

PCN Num	PCN Number: 20170609001A				PCI	N Date:	July 18, 2018	
Title: Qualification of TIPI as additional Assembly and Test Site for Select Devices				ces				
Customer Contact: PCN Manager Dept: Quality Services								
Change Type:								
Assei	mbly Site			Design			Wafer Bu	ımp Site
Assei	mbly Process			Data Shee	et		Wafer Bu	ımp Material
Assei	mbly Materials			Part numb	er change		Wafer Bu	ımp Process
Mech	anical Specific	ation	\boxtimes	Test Site			Wafer Fa	b Site
Packi	ng/Shipping/L	abeling		Test Proce	ess		Wafer Fa	b Materials
	☐ Wafer Fab Process				b Process			
PCN Details								

PCN Details

Description of Change:

Revision A is to update the description of change to provide correction on the pin 1 marking differences between sites. We apologize for any inconvenience this may have caused.

Qualification of TIPI (TI Philippines) as additional Assembly and Test Site for Select Devices listed in the "Product Affected" Section. Current assembly sites and Material differences are as follows.

Assembly Site	Assembly Site Origin	Assembly Country Code	Assembly Site City
JCET Co. Ltd	JCE	CHN	Jiangyin
TI Philippines A/T	PHI	PHL	Baguio City

Material Differences:

	JCET	TIPI
Mold compound	120800005407	4222198
Lead finish	Matte Sn	NiPdAu

Pin 1 Marking Differences:

	JCET	TIPI
Pin 1 Marking	* * * * * 3201 o * * * * o = Pin 1 (Marked) **** = Binary Date Code per TI drawing	[] * * * * * [] 3201 [] * * * * [] = Pin 1 (Marked) **** = Binary Date Code per TI drawing

Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Anticipated impact on Material Declaration

No Impa Material	ct to the Declaration		production of release. Up obtained fro	lata and will be ava on production relea m the <u>TI Eco-Info</u> eting current regul	ct Content reports are driven from ailable following the production ase the revised reports can be website. There is no impact to the atory compliance requirements
Changes to p	roduct iden	tificat	ion resulting	g from this PCN:	
Assembly S	ite				
	ET Co. Ltd		Assembly S	Site Origin (22L)	ASO: JCE
TI Ph	ilippines A/T			Site Origin (22L)	ASO: PHI
Texas					
Product Affe	TE CODES: J	CET =	F, TIPI = W		
Product Arre		CET =	F, TIPI = W		
	cted:		·	TPS562208DDCR	TPS563201DDCT
TPS561201D TPS561201D	cted: DCR TP	S5612	F, TIPI = W 08DDCT 01DDCR	TPS562208DDCR TPS562208DDCT	TPS563201DDCT TPS563208DDCR

Qualification Data TIPI SOT: Phase 3 (DDC_FC0L_JCAP Bump)

Approve Date 07-Jun-2017

Product Attributes

Attributes	Qual Device: TPS562201DDCR		
Assembly Site	PHI (TIPI)		
Package Family	SOT		
Flammability Rating	UL 94 V-0		
Wafer Fab Supplier	MIHO8		
Wafer Fab Process	LBC7.3		

⁻ QBS: Qual By Similarity

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TPS562201DDCR
ED	Electrical Characterization	Per Datasheet Parameters	Pass

⁻ Qual Device TPS562201DDCR is qualified at LEVEL1-260C

FLAM	Flammability (UL 94V-0)		3/15/0
HAST	Biased HAST, 130C/85%RH	96 Hours	3/231/0
HTOL	Life Test, 125C	1000 Hours	3/231/0
HTSL	High Temp Storage Bake 170C	420 Hours	3/231/0
LI	Lead Fatigue	Leads	3/66/0
LI	Lead Pull	Leads	3/66/0
MISC	Salt Atmosphere		3/66/0
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	Pass
MQ	Manufacturability (Bump)	(per mfg. Site specification)	Pass
PD	Physical Dimensions		3/15/0
SD	Solderability	8 Hours Steam Age	3/36/0
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0
UHAST	Unbiased HAST 130C/85%RH	96 Hours	3/231/0

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles Quality and Environmental data is available at Tl's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

Qualification Data TIPI SOT: Phase3 (DDC_FCOL_JCAP_Bump_TPS563201DDCR)

Approve Date 08-Jun-2017

Product Attributes

Attributes	Qual Device: TPS563201DDCR
Assembly Site	PHI (TIPI)
Package Family	SOT
Flammability Rating	UL 94 V-0
Wafer Fab Supplier	MIHO 8
Wafer Fab Process	LBC7.3

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	TPS563201DDCR
LI	Lead Fatigue	Leads	3/66/0
LI	Lead Pull	Leads	3/66/0
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	Pass
MQ	Manufacturability (Bump)	(per mfg. Site specification)	Pass
PD	Physical Dimensions		3/15/0
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0

⁻ Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com